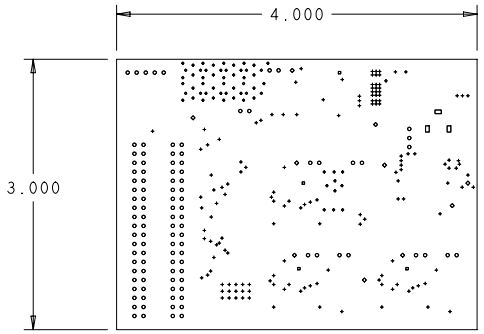
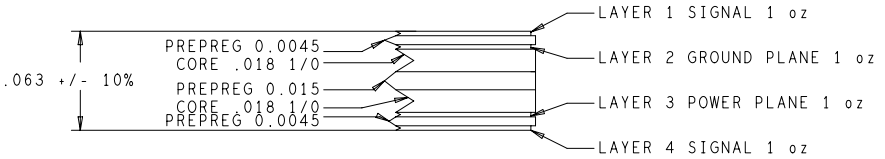
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	ALPHA RELEASE	11/17/10	RWF
2	ALPHA RELEASE	12/22/10	RWF
3	BETA RELEASE	1/12/11	RWF



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	10.0	+3.0/-3.0	PLATED	150
·	18.0	+3.0/-3.0	PLATED	61
▫	20.0	+0.0/-0.0	PLATED	4
○	40.0	+3.0/-3.0	PLATED	104
◇	43.0	+3.0/-3.0	PLATED	10
▭	70.0x40.0	+3.0/-3.0	PLATED	1
▯	70.0x40.0	+3.0/-3.0	PLATED	2

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN ETCH (PREFERRED) OR SILKSCREEN.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES		
TOLERANCES ON; ANGLES +/- 2°	DRAWN ZMK	11/10/10
2 PL DECIMALS +/- .010	CHECKED RWF	11/17/10
3 PL DECIMALS +/- .005	ENGRG RWF	11/10/10
THIRD ANGLE PROJECTIONS	ISSUED	

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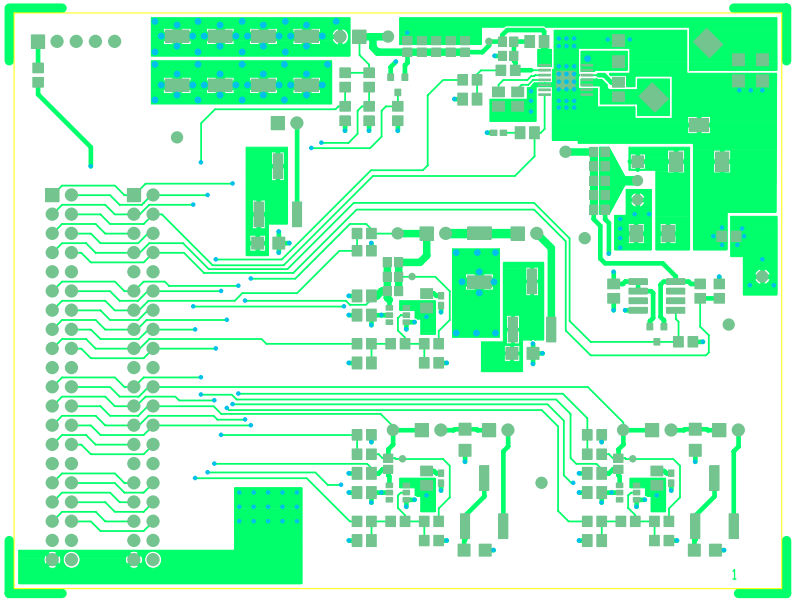
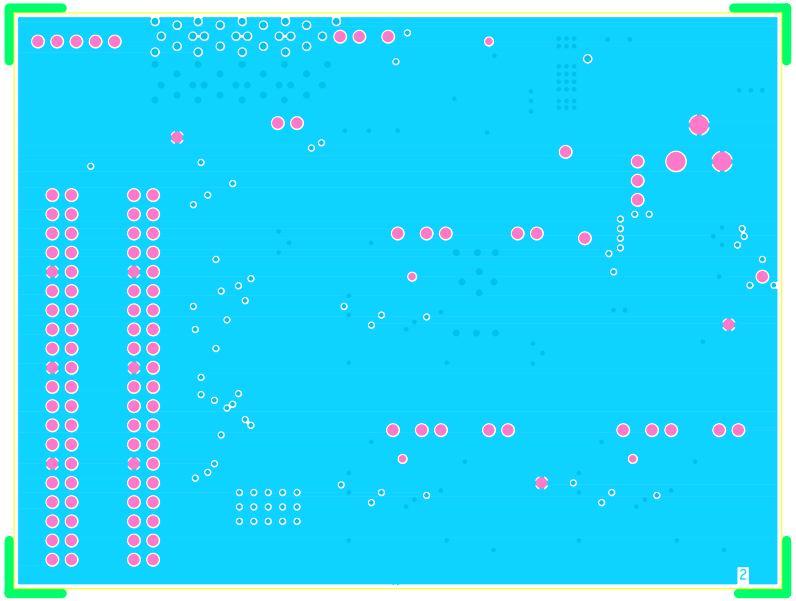
FABRICATION DRAWING KIT-035 PSoC POWER MANAGEMENT EBK

SIZE	FSCM NO	DWG NO	REV
C		PDC-09606	3

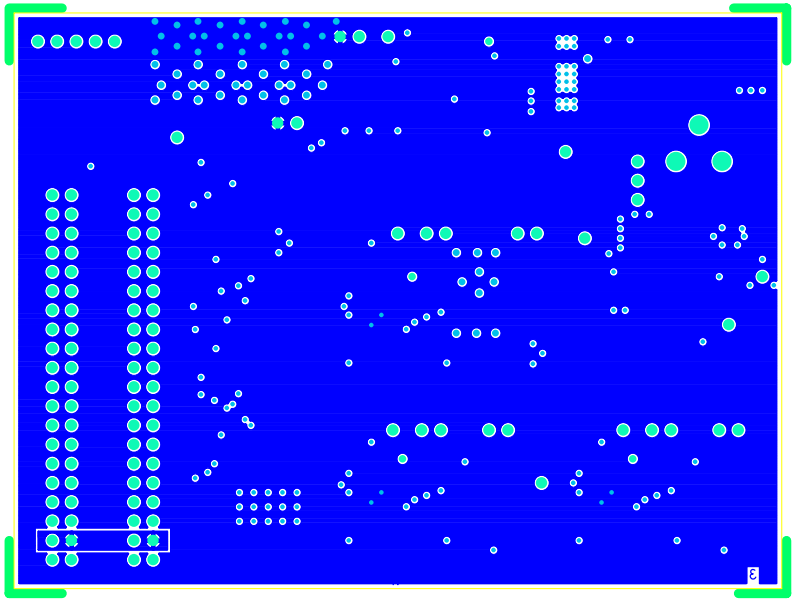
SCALE: 1/1 SHEET: 1 OF 1



PDC-09606 REV 3 PRIMARY SIDE

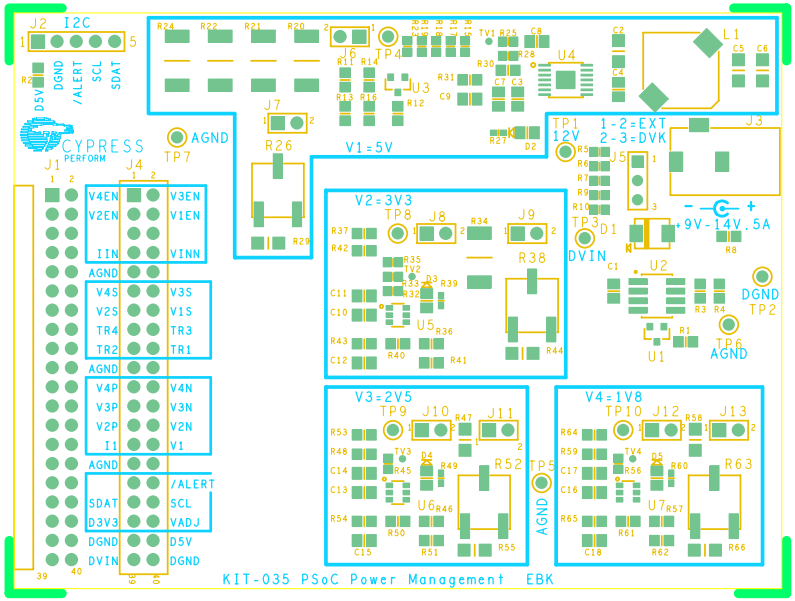


PDC-09606 REV 3 GROUND LAYER



PDC-09606 REV 3 POWER PLANE

PDC-09606 REV 3 SECONDARY SIDE



PDC-09606 REV 3 PRIMARY SILKSCREEN